

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant:	Wolfgang Hetzel et al.	Examiner:	James M. Mitchell
Serial No.:	10/577,173	Group Art Unit:	2813
Filed:	April 26, 2006	Docket No.:	I441.141.101/QIM4346
Title:	SEMICONDUCTOR DEVICE WITH PLASTIC PACKAGE MOLDING COMPOUND, SEMICONDUCTOR CHIP AND LEADFRAME AND METHOD FOR PRODUCING SAME		

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**AMENDMENT AND RESPONSE**

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

This Amendment and Response is in reply to the Non-Final Office Action mailed September 3, 2010. Please amend the above-identified patent application as follows: